

01/31/02
1131 U.S. PTO

DELPHI TECHNOLOGIES, INC.
Legal Staff
P.O. Box 5052
Mail Code: 480-414-420
Troy, Michigan 48007-5052

10-9-01

11017 U.S. PTO
10/059404
01/31/02

Assistant Commissioner for Patents
Box Patent Application
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No.: DP-305004

Inventors : MIKEL R. FULK
JASON M. KEY
DANIEL A. LAWLYES
JACK A. BEDNARZ

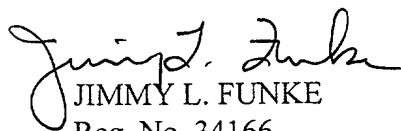
Title : HIGH DENSITY WIRE BONDABLE CONNECTOR ASSEMBLY

Filing Fee Formula

Basic Fee.....	\$ 740.00
Additional Fees:	
Number of independent claims in excess of 3, times \$80.00	\$ 0.00
Number of claims in excess of 20, times \$18.00.....	\$ 0.00
Multiple dependent claim, add \$270.00	\$ 0.00
Total Filing Fee.....	\$ 740.00

The patent specification DP-305004 entitled HIGH DENSITY WIRE BONDABLE CONNECTOR ASSEMBLY and filed in the Patent and Trademark Office herewith is the patent specification for which the inventor(s) executed the Declaration enclosed herewith.

Please charge the \$ 740.00 filing fee to DELPHI TECHNOLOGIES INC. Deposit Account No. 50-0831.


JIMMY L. FUNKE
Reg. No. 34166
(248) 267-5554

Enclosures

10059404-013102

DELPHI

Automotive Systems

P. O. Box 9005

Kokomo, Indiana

46904-9005

4407

First Class Mail

1017 U.S. PTO

10/059404



01/31/02

ASSISTANT COMMISSIONER FOR PATENTS

BOX PATENT APPLICATIONS

WASHINGTON, D C

20251

RETURN TO SENDER

NO POSTAGE
NECESSARY
IF MAILED
IN THE
UNITED STATES

HMS